



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-11-09
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T1235H-6G-TR	7BD1*126SBM1	A	3068	2018-11-09
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-10.5-1.27	3	gull wing	
Comment	D2PAK CLIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.32	Die - Leadframe	234
Lead	29.81	Soft solder	21598
Lead-Borate Glass	1.50	Die	1088

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	28.30	Die - Soft solder	20510
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	23.31	Die	762845
Lead	1000 ppm	6.49	Soft solder	920351

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	78D1*12658M1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	30.558	mg	supplier	die	Silicon (Si)	7440-21-3		6.850	mg	224164	4964
				supplier	metallization	Gold (Au)	7440-57-5		0.026	mg	851	19
				supplier	metallization	Nickel (Ni)	7440-02-0		0.137	mg	4483	99
				JIG - R	Passivation	Lead (Pb)	7439-92-1	7c-4-Electrical and e	21.810	mg	713725	15804
				supplier	Passivation	Silicon Oxide	7631-86-9		0.039	mg	1275	28
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	295	7
Leadframe	M-004 Copper and its alloys	700.748	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.186	mg	6087	135
				JIG - R & California 65	glass coating	Lead-Borate Glass	65997-18-4	7c-4-Electrical and e	1.501	mg	49120	1088
				supplier	alloy	Copper (Cu)	7440-50-8		699.837	mg	998700	507128
				supplier	alloy	Iron (Fe)	7439-89-6		0.701	mg	1000	508
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.210	mg	300	152
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	6.494	mg	920351	4706
Soft solder	Solder	7.056	mg	supplier	solder	Silver (Ag)	7440-22-4		0.176	mg	24943	128
				supplier	solder	Tin (Sn)	7440-31-5		0.351	mg	49745	254
				supplier	solder	flux residue	Proprietary		0.035	mg	4961	25
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	6.494	mg	920351	4706
Encapsulation	M-011 Other inorganic materials	603.699	mg	supplier	mold compound	Silica, vitreous	60676-86-0		458.811	mg	760000	332472
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		61.577	mg	102000	44621
				supplier	mold compound	Phenol resin	9003-35-4		36.222	mg	60000	26248
				supplier	mold compound	Others	Proprietary		30.185	mg	50000	21873
				supplier	mold compound	Metal hydroxide	Proprietary		12.074	mg	20000	8749
				supplier	mold compound	Carbon black	1333-86-4		4.830	mg	8000	3500
connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	4575
clip	M-004 Copper and its alloys	31.625	mg	supplier	alloy	Copper ( Cu)	7440-50-8		31.625	mg	1000000	22917